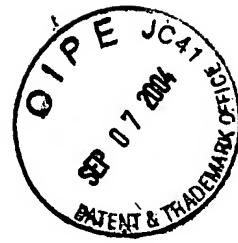


IFW

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No: 10/621,987 Docket No: 2011118
Filing Date: 07/16/2003 Applicant: Jackson Hsieh
Examiner: SOWARD, IDA M Art Unit: 2822
Title: SUBSTRATE STRUCTURE FOR AN INTEGRATED CIRCUIT PACKAGE
AND METHOD FOR MANUFACTURING THE SAME

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

TRANSMITTAL OF AMENDMENT

1. Transmitted herewith is a response to an office action for this application prepared and submitted by the Applicant.
2. Applicant is entitled to Small Entity Status.
3. The proceedings herein are for a patent application and the provisions of 37 CFR 1.136 apply. Applicant believes that no extension of time is required. However, a conditional petition is hereby made to provide for the possibility that applicant has inadvertently overlooked the need for a petition for extension of time.
4. No fee is required at this time.
5. Certificate of Mailing (37 CFR 1.8a): I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Non-Fee Amendment, Commissioner for Patents, P.O. Box 1450, Arlington, VA 22313-1450.

Respectfully submitted,



Keith Kline
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appl. No. 10/621,987

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Art Unit: 2822

SUBSTRATE STRUCTURE FOR AN INTERGRATE PACKAGE

Title

THE ASSISTANT COMMISSIONER FOR PATENTS

To: Washington, D.C. 20231

RESPONSE TO OFFICE ACTION

Dear Sir:

In response to the Office Action dated 06/29/2004, Applicant submits the
5 following amendments and remarks.

AMENDMENTS

IN THE CLAIMS:

Please cancel claims 5 and 6.

Please rewrite claim1-3 as follows :

10 1. A substrate structure for an integrated circuit package to be electrically connected to a printed circuit board, the substrate structure comprising:

a plurality of lower metal sheets arranged in an array, each of the lower metal sheets having an upper surface and a lower surface;

15 a plurality of upper metal sheets arranged in an array, each of the upper metal sheets having an upper surface and a lower surface, the lower surfaces of the upper metal sheets being stacked on the upper surfaces of the lower metal sheets; and